

WHAT IS CLAIMED IS:

1. A mold for forming a molded part, comprising:
 - a baseplate;
 - at least one pot formed in the baseplate for receiving a mold compound;
 - 5 at least one cavity formed in the baseplate and adapted to receive a microelectronic device; and
 - at least one channel system formed in the baseplate and coupled to the at least one pot and further coupled to the at least one cavity;
 - 10 at least one first channel formed in the baseplate and coupled to the at least one channel system and separated from the at least one cavity by the at least one channel system.

2. The mold of Claim 1, wherein the channel system comprises a second channel coupled to a third channel.

- 15 3. The mold of Claim 1, further comprising a microelectronic device disposed within at least one cavity.

4. The mold of Claim 3, wherein the microelectronic device comprises a
20 semiconductor device.

5. The mold of Claim 3, wherein the at least one cavity is adapted to form an encapsulation of the mold compound around the microelectronic device.

- 25 6. The mold of Claim 1, wherein the at least one first channel is coupled to the at least one channel system between the pot and the at least one cavity.

7. The mold of Claim 1, further comprising at least one vent coupled to
the at least one first channel, the at least one vent adapted to vent air expelled from the
30 mold compound.

8. The mold of Claim 1, wherein the at least one first channel is substantially perpendicularly coupled to the at least one channel system.

9. A mold for forming a molded part, comprising:
 - a baseplate;
 - at least one pot formed in the baseplate for receiving a mold compound;
 - at least one sprue channel formed in the baseplate and coupled to the at least one pot;
 - at least one cavity formed in the baseplate and adapted to receive a microelectronic device;
 - at least one runner channel formed in the baseplate and coupling the at least one sprue channel to the at least one cavity;
 - 10 at least one dummy runner channel formed in the baseplate and coupled to the at least one sprue channel, the at least one dummy runner channel separated from the at least one cavity by the at least one sprue channel; and
 - at least one vent coupled to the at least one dummy runner channel, the at least one vent adapted to vent air expelled from the mold compound.
- 15 10. The mold of Claim 9, further comprising a microelectronic device disposed within at least one cavity.
11. The mold of Claim 10, wherein the microelectronic device comprises a 20 semiconductor device.
12. The mold of Claim 10, wherein the at least one cavity is adapted to form an encapsulation of the mold compound around the microelectronic device.
- 25 13. The mold of Claim 9, wherein the at least one dummy runner channel is coupled to the at least one sprue channel between the pot and the at least one cavity.
14. The mold of Claim 9, further comprising at least one vent coupled to the at least one dummy runner channel, the at least one vent adapted to vent air expelled 30 from the mold compound.

15. The mold of Claim 9, wherein the at least one dummy runner channel is substantially perpendicularly coupled to the sprue channel.

16. A method for forming a molded part, comprising:
 - placing a mold compound into at least one pot of a mold;
 - pushing a portion of the mold compound through at least one sprue channel coupled to the at least one pot;
 - 5 pushing a portion of the mold compound into at least one dummy runner channel coupled to the at least one sprue channel runner, the at least one dummy runner channel separated from at least one cavity by the at least one sprue channel;
 - venting air expelled from the mold compound through at least one vent coupled to the at least dummy runner channel;
 - 10 pushing a portion of the mold compound through at least one runner channel and into the least one cavity adapted to receive a microelectronic device, the at least one runner channel coupled to the at least one sprue channel and further coupled to the at least one cavity; and
 - curing the mold compound to form the molded part.
- 15
17. The method of Claim 16, further comprising disposing a microelectronic device within the at least one cavity.
18. The method of Claim 17, wherein the microelectronic device
20 comprises a semiconductor device.
19. The method of Claim 17, further comprising forming an encapsulation of the mold compound around the microelectronic device.
- 25
20. The method of Claim 16, wherein the at least one dummy runner channel is coupled to the at least sprue channel between the pot and the at least one cavity.